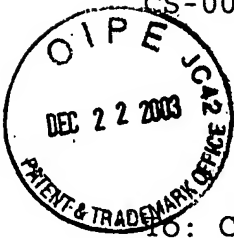


CS-00-153CB



December 17, 2003

TO: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject: | Serial No. 10/679,736 10/06/03 |
Yeung-Way Teh et al.
A NOVEL COPPER METAL STRUCTURE FOR
THE REDUCTION OF INTRA-METAL
CAPACITANCE
| ----- |

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450, on December 19, 2003.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

 12/19/03

CS-00-153CB

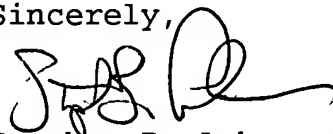
U.S. Patent 5,109,267 to Koblinger et al., "Method for Producing an Integrated Circuit Structure with a Dense Multilayer Metallization Pattern," discloses a sloped metallization.

U.S. Patent 5,821,141 to Huang, "Method for Forming a Cylindrical Capacitor in DRAM Having Pin Plug Profile," discloses a capacitor with a rounded top opening.

The following three U.S. Patents disclose interconnect shaped and processes:

- 1) U.S. Patent 4,888,087 to Moslehi et al., "Planarized Multilevel Interconnection for Integrated Circuits."
- 2) U.S. Patent 6,114,243 to Gupta et al., "Method to Avoid Copper Contamination on the Sidewall of a Via or a Dual Damascene Structure."
- 3) U.S. Patent 6,103,619 to Lai, "Method of Forming a Dual Damascene Structure on a Semiconductor Wafer."

Sincerely,



Stephen B. Ackerman,
Reg. No. 37761

Form PTO-1449

Docket Number (Sequence)

Application Number

CS-00-153CB

10/679,736

Applicant

Yeung-Way Teh et al.

Filing Date

10/06/03

Group Art Unit

INFORMATION DISCLOSURE CITATION IN AN APPLICATION

(Use several sheets if necessary)

U. S. PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	PLUNG DATE IF APPROPRIATE
51092674	28/92	Koblinger et al.	357	54	7/17/91
5821141	10/13/98	Huang	438	253	1/12/98
4888087	12/19/89	Moslehi et al.	156	643	12/13/88
6114243	9/5/00	Gupta et al.	438	687	11/15/99
6103619	8/15/00	Lai	438	638	10/8/99

FOREIGN PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
					YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.